Microsemi Corporation

April 18, 2016

Product/Process Change Notification No: ESC-2160666, Issue 1

Change Classification: Major

Subject:

Notice of Change – PM4329 Flip Chip Conversion

Description of Change:

PM4329-BI and PM4329-BGI will change from a wire-bond package to a FCBGA package. The change will require a part number change. PM4329-BI will be replaced with PM4329-FXI, and PM4329-BGI will be replaced with PM4329-FEI.

Reason for Change:

PM4329 is currently assembled in cavity down (wire-bond) package. The suppliers for the cavity down substrate are currently in the process of phasing out its production due to declining demand. In order to extend the life cycle for this device, and provide better supply continuity, Microsemi has converted the package design to the more mainstream FCBGA package type. Devices in the FCBGA package have passed standard product qualification and characterization.

Application Impact:

The change to the FCBGA package does not affect the function of the device. The device footprint remains the same, but the overall device thickness will change. The package new package thickness is provided in the Appendix.

Method of Identifying Changed Product:

The FCBGA components can be identified by the device suffix FXI & FEI, which is branded on the device.

Products Affected by this Change:

Affected Part Numbers	Replacement Part Number	Ball Composition	RoHS Status of Replacement Part
PM4329-BI	PM4329-FXI	PbSn	RoHS 6/6 with exemption 7b
PM4329-BGI	PM4329-FEI	SAC305	RoHS 6/6

Production Shipment Schedule:

Qualification report	Available
Samples	Available by Request for PM4329-FEI
Deadline for customer response	May 18, 2016
Production shipment start for changed parts *	July 18, 2016

*** PM4329-BI & PM4329-BGI will no longer be orderable part numbers after the PCN expiry date**

IMPORTANT NOTICE: PMC-Sierra was acquired by Microsemi on Jan. 15th 2016. For the interim please ensure that you maintain your system for the product(s) listed under the vendor name of PMC-Sierra and or Wintegra Ltd. Further information on the integration of PMC-Sierra as Microsemi will be provided in the near future.

Contact Information:

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Regards,

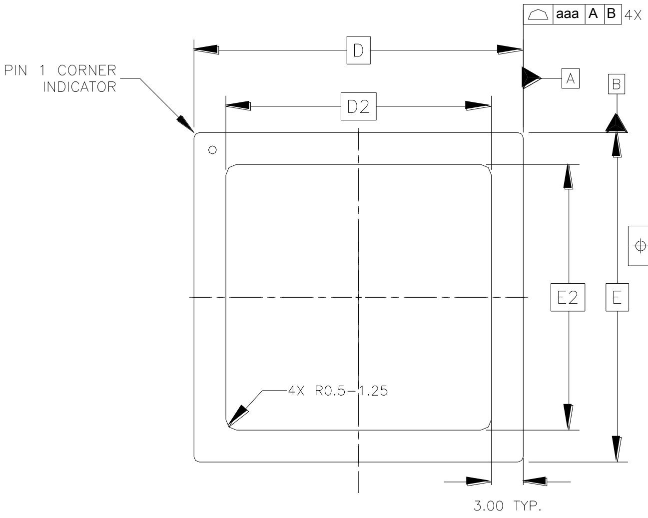
Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

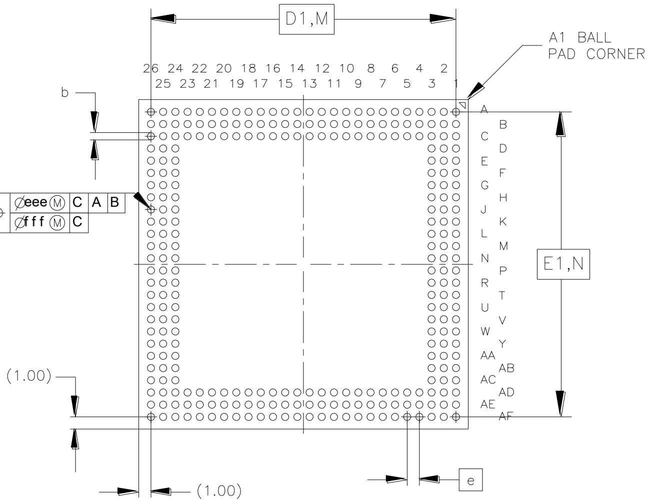
This Product/Process Change Notification is confidential and proprietary information of Microsemi and is intended only for distribution by Microsemi to its customers, for customers' use only. It must not be copied or provided to any third party without Microsemi's prior written consent.

4) DIMENSION ddd DENOTES COPLANARITY
5) PACKAGE COMPLIANT TO JEDEC REGISTERED OUTLINE MS-034 VARIATION AAL-1
WITH THE EXCEPTION OF TOTAL BALL COUNT

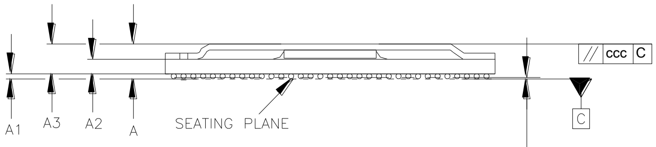
PACKAGE TYPE: 276 FLIP CHIP BALL GRID ARRAY - FCBGA (HDBU 1-2-1)																		
BODY SIZE: 27 x 27 x 2.44mm																		
Dim.	A	A1	A2	A3	D	D1	E	E1	D2	E2	M, N	e	b	aaa	ccc	ddd	eee	f f f
Min.	2.25	0.40	-	1.85	-	-	-	-	-	-	-	-	0.50	-	-	-	-	-
Nom.	2.44	0.50	0.60 REF	1.94	27.00 BSC	25.00 BSC	27.00 BSC	25.00 BSC	21.00 BSC	21.00 BSC	26x26	1.00 BSC	0.64	-	-	-	-	-
Max.	2.65	0.60	-	2.05	-	-	-	-	-	-	-	-	0.70	0.20	0.35	0.20	0.25	0.10



TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES: 1) ALL DIMENSIONS IN MILLIMETERS
2) DIMENSION aaa DENOTES PACKAGE PROFILE
3) DIMENSION bbb and ccc DENOTE PARALLELISM
4) DIMENSION ddd DENOTES COPLANARITY
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Min.	2.25	0.40	-	1.85	-	-	-	-	-	-	-	-	0.50	-	-	-	-	-
Nom.	2.44	0.50	0.60 REF	1.94	27.00 BSC	25.00 BSC	27.00 BSC	25.00 BSC	21.00 BSC	21.00 BSC	26x26	1.00 BSC	0.64	-	-	-	-	-
Max.	2.65	0.60	-	2.05	-	-	-	-	-	-	-	-	0.70	0.20	0.35	0.20	0.25	0.10